

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	2608	257/774.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	3040	257/778.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	2304	257/737.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	4463	Chip adj scale adj package	US-PGPUB; USPAT; USOCR
5	BRS	L5	220	257/774.ccls.	EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	129	257/778.ccls.	EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	2	((chip or device or die) and (substrate or interposer) and solder and (via or hole) and conduct\$3 and (protrud\$3 or project) and (pad or terminal or electrode) and (trace or wiring) and (flip or inverted)).clm.	US-PGPUB